

TECHNICAL DATA SHEET

SLIDE®

#468

KLENZ Purging Compound

KLENZ Purging Compound 468-45, 468-1000

Product Description

KLENZ is a revolutionary purging compound requiring no mixing or preparation time. With operating temperatures of 330° - 610°F, KLENZ thoroughly cleanses hot runners and the barrel, helping to eliminate color streaking and black specks. Formulated with a polyolefin resin carrier, KLENZ purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

Applications

Purging Compound

Unit Package Description

48 and 1,100 pound boxes

Generic Description

Purging Compound

Net Weight Fill

45 & 1,000 pounds

UPC Code

858799000684

Appearance

Resin Pellet

Odor

None

Flash Point F

>750 degrees

Flash Point C

>400 degrees

Base Type

Resin

Evaporation Rate

N/A

HMIS Rating

0, 0, 0, None

DOT Proper Shipping Name

Not regulated, Granules, NOI

Removal

N/A

Units Per Case

45 & 1,000 pounds

Case Weight (lbs)

45 / 1,000

Working Temperature F

330 to 610 degrees

Working Temperature C

165 to 321 degrees

Propellant

N/A

NFPA Aerosol Flammability Level

N/A

